

LTM8028-BGA, 66LD 15mm X 15mm X 4.92mm (TABLE OF MATERIAL DECLARATION)

The LTM8028 is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.2510	Barium Compounds	7727-43-7	0.00645	2.57
				Bismaleimide/Triazine Resin/Filler Substances (Silica Crystalline)	105391-33-1,1156-51-0/9003-36-5/21645-51-2,non-disclosure	0.04802	19.13
				Copper Metal	7440-50-8	0.14183	56.50
				Copper Compounds	147-14-8	0.00006	0.02
				Ecotoxic substances	7440-38-2, 7440-28-0	0.00003	0.01
				Gold metal or alloy	7440-57-5	0.00040	0.16
				Nickel	7440-02-0	0.00188	0.75
				Zinc	7440-66-6	0.00028	0.11
				Continuous Filament Fiber Glass	65997-17-3	0.03775	15.04
				Acrylic Resin	non-disclosure	0.01227	4.89
				Epoxy Resin	non-disclosure	0.00005	0.02
				Chromium(III) Oxide	1308-38-9	0.00001	0.00
				Silica amorphous	7631-86-9	0.00014	0.05
				Talc;not containing fibers like asbestos	14807-96-6	0.00075	0.30
				Aromatic Carbonyl compounds	non-disclosure	0.00070	0.28
				Cyanoguanidine	461-58-5	0.00002	0.01
				Calcium caobonate	471-34-1	0.00001	0.00
Amine compounds	non-disclosure	0.00010	0.04				
Leveling agent and others	non-disclosure	0.00028	0.11				
2	Solder Paste	Alloy	0.0116	Sn	7440-31-5	0.01099	95.00
				Sb	7440-36-0	0.00058	5.00
3	Epoxy		0.0007	Di-ester resin	non-disclosure	0.00006	8.00
				Functionalized ester	non-disclosure	0.00006	8.00
				Silver	7440-22-4	0.00060	84.00
4	Passive/Active Components		0.8350	Iron Powder (Fe)	7439-89-6	0.59465	71.22
				Copper (Cu)	7440-50-8	0.17032	20.40
				Nickel (Ni)	7440-02-0	0.00836	1.00
				Tin (Sn)	7440-31-5	0.00683	0.82
				Ceramic (Ba) Compounds	12047-27-7	0.05484	6.57
5	Active Ics	Silicon	0.0097	Silicon	7440-21-3	0.00968	100.00
6	Wire	Gold	0.0038	Au	7440-57-5	0.00377	99.99
7	Solder Ball	SAC305	0.1924	Sn	7440-31-5	0.18567	96.50
				Ag	7440-22-4	0.00577	3.00
				Cu	7440-50-8	0.00096	0.50
8	Encapsulation	Epoxy Resin	1.5102	Fused Silica	60676-86-0	1.16590	77.20
				Epoxy Resin	non-disclosure	0.13441	8.90
				Phenol Resin	non-disclosure	0.13441	8.90
				Crytalline Silica	14808-60-7	0.04531	3.00
				Carbon Black	1333-86-4	0.00755	0.50
				Metal Hydroxide	non-disclosure	0.02265	1.50
Total Package Weight			2.8144				

Note: Composition derived from MSDS and material C of C from Vendors; Component Weight based on assembly of generic parts